

PRELIMINARY INFORMATION

Description

The μ PB100474A is a very high-speed 100K interface ECL RAM. It is organized as 1K words by 4 bits with noninverted, open emitter outputs and full voltage and temperature compensation. The device is packaged in a 24-pin cerdip or flatpack.

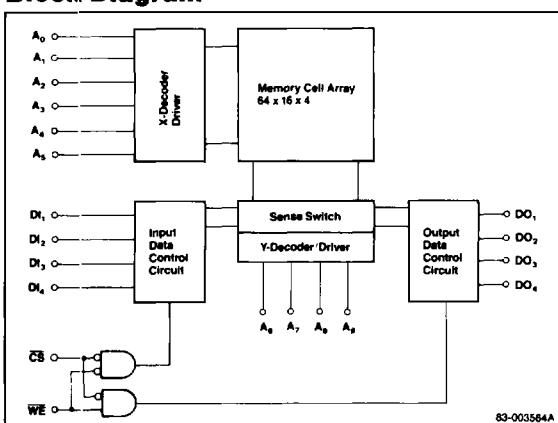
Features

- 1K-word by 4-bit organization
- 100K ECL interface
- Full voltage and temperature compensation
- Open emitter outputs (noninverted)
- Fast access times
- 24-pin cerdip and flatpack packaging

Ordering Information

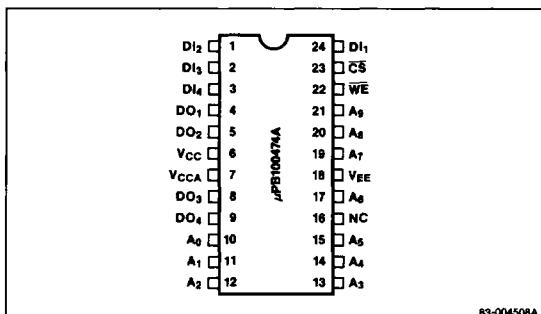
Part Number	Access Time (max)	Supply Current (min)	Package
μ PB100474AB-5	5 ns	-250 mA	24-pin ceramic flatpack
AB-7	7 ns		
μ PB100474AD-5	5 ns	-250 mA	24-pin cerdip
AD-7	7 ns		

Block Diagram

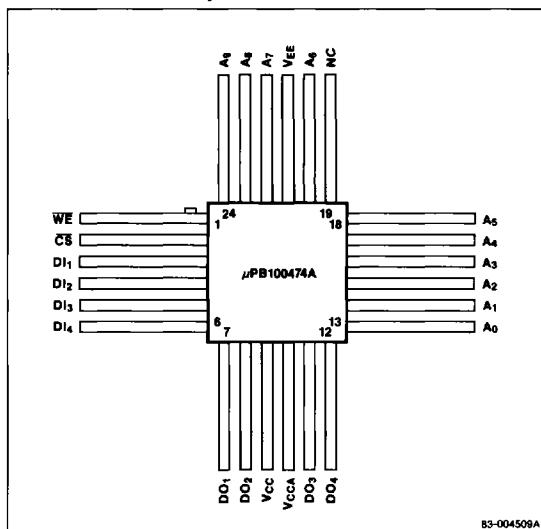


Pin Configurations

24-Pin Cerdip



24-Pin Ceramic Flatpack



Pin Identification

Symbol	Function
A ₀ -A ₃	Address inputs
D _I ₁ -D _I ₄	Data inputs
D _O ₁ -D _O ₄	Data outputs
WE	Write enable
CS	Chip select
V _{CC}	Power supply (current switches and bias driver)
V _{CCA}	Power supply (output devices)
V _{EE}	-4.5-volt power supply
NC	No connection

Absolute Maximum Ratings

Supply voltage, V _{EE} to V _{CC}	-7.0 to +0.5 V
Input voltage, V _{IN}	V _{EE} to +0.5 V
Output current, I _{OUT}	-30 to +0.1 mA
Storage temperature, T _{STG} Under bias, T _{STG} (Bias)	-65 to +150°C -55 to +125°C

Comment: Exposure to Absolute Maximum Ratings for extended periods may affect device reliability; exceeding the ratings could cause permanent damage. The device should be operated within the limits specified under DC and AC Characteristics.

Truth Table

CS	WE	D _{IN}	Output	Mode
H	X	X	L	Not selected
L	L	L	L	Write 0
L	L	H	L	Write 1
L	H	X	D _{OUT}	Read

Notes:

(1) X = don't care.

DC CharacteristicsT_A = 0 to +85°C; V_{EE} = -4.5 V; output load = 50 Ω to -2.0 V; V_{CC} = V_{CCA} = 0 V

Parameter	Symbol	Limits			Test Conditions
		Min	Typ	Max	
Output voltage, high	V _{OH}	-1025	-880	mV	V _{IN} = V _{IH} (max) or V _{IL} (min)
Output voltage, low	V _{OL}	-1810	-1620	mV	V _{IN} = V _{IH} (max) or V _{IL} (min)
Output threshold voltage, high	V _{OHC}	-1035		mV	V _{IN} = V _{IH} (min) or V _{IL} (max)
Output threshold voltage, low	V _{OCL}		-1610	mV	V _{IN} = V _{IH} (min) or V _{IL} (max)
Input voltage, high	V _{IH}	-1165	-880	mV	
Input voltage, low	V _{IL}	-1810	-1475	mV	
Input current, high	I _{IH}		220	μA	V _{IN} = V _{IH} (max)
Input current, low	I _{IL}	0.5	170	μA	For CS: V _{IN} = V _{IL} (min)
			-50	μA	For all others: V _{IN} = V _{IL} (min)
Supply current	I _{EE}	-250		mA	All inputs and outputs open

Notes:

- (1) The device under test (DUT) is mounted in a test socket and is measured at a thermal equilibrium established with a transverse air flow maintained at greater than 2.0 m/sec.

Capacitance

Parameter	Symbol	Limits			Test Conditions
		Min	Typ	Max	
Input capacitance	C _{IN}		4	pF	
Output capacitance	C _{OUT}		5	pF	

Figure 1. Loading Conditions Test Circuit

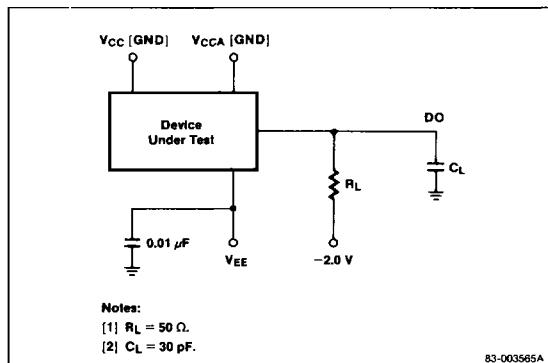
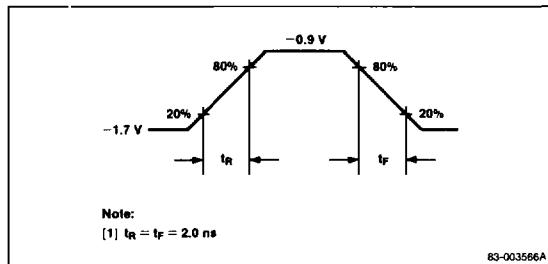


Figure 2. Input Pulse

**AC Characteristics**

$T_A = 0$ to $+85^\circ\text{C}$; $V_{EE} = -4.5 \text{ V} \pm 5\%$; output load = 50Ω to -2.0 V ; $V_{CC} = V_{CCA} = 0 \text{ V}$

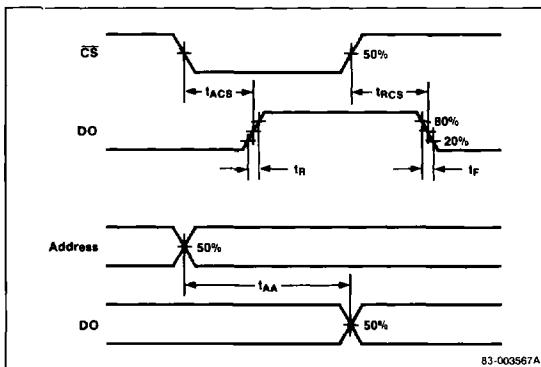
Parameter	Symbol	Limits			Unit
		μPB100474A-5	μPB100474A-7		
Read Mode					
Address access time	t_{AA}		5	7	ns
Chip select access time	t_{ACS}		3	5	ns
Chip select recovery time	t_{RCS}		3	5	ns
Write Mode					
Write pulse width	t_W	5	7		ns
Data setup time	t_{WSD}	1	1		ns
Data hold time	t_{WHD}	1	1		ns
Address setup time	t_{WSA}	1	1		ns
Address hold time	t_{WHA}	1	1		ns
Chip select setup time	t_{WSCS}	1	1		ns
Chip select hold time	t_{WHCS}	1	1		ns
Write disable time	t_{WS}		3	5	ns
Write recovery time	t_{WR}		6	8	ns
Rise and Fall Times					
Output rise time	t_R	2	2		ns
Output fall time	t_F	2	2		ns

Notes:

- (1) The device under test (DUT) is mounted in a test socket and is measured at a thermal equilibrium established with a transverse air flow maintained at greater than 2.0 m/sec .
- (2) See figures 1 and 2 for loading conditions and input pulse timing. Input pulse levels = -1.7 to -0.9 V ; input rise and fall times (measured between 20% and 80% or 80% and 20%) = 2 ns ; input and output timing reference levels = 50%.

Timing Waveforms

Read Mode



Write Mode

